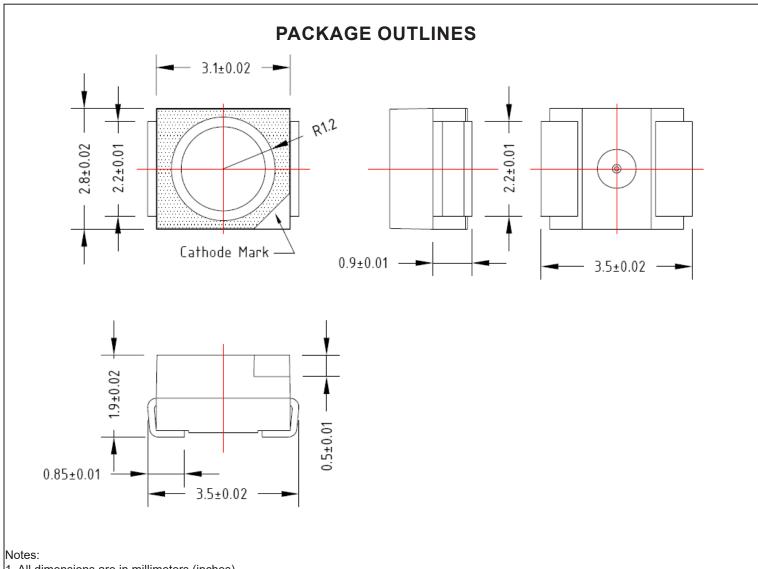


SPECIFICATION CSP1311B2C



1. All dimensions are in millimeters (inches).

- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CSP1311B2C	InGaN	Blue	Water Clear	120°	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	VR	10	μΑ	
Power Dissipation	Pd	72	mW	
Operating Temperature Range	Тор	-30~+100	°C	
Storage Temperature Range	Тѕтс	-40~+100	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	100	mA	
Soldering Temperature	TsoL	Max 260°C for 10 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol	Toot Condition	Value			l loit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	180	300	-	mcd
Forward Voltage	VF	IF = 20mA	1	3.2	3.5	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	-	120	-	Deg
Peak Wavelength	λР	IF = 20mA	ı	465	-	nm
Dominant Wavelength	λD	IF = 20mA	460	470	480	nm

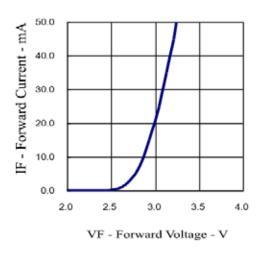
^{*}Tolerance of viewing angle: -10 / +5 deg.



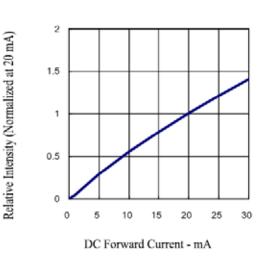


OPTICAL CHARACTERISTIC CURVES

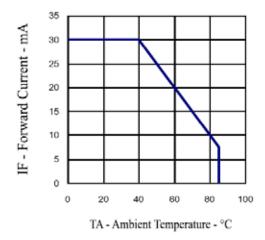
Forward Current vs. Forward Voltage



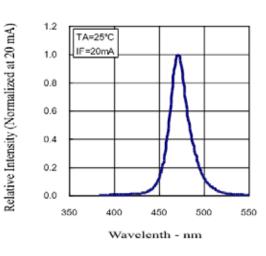
Relative Intensity vs. Forward Current



Forward Current vs. Ambient Temperature



Relative Intensity vs. Wavelength

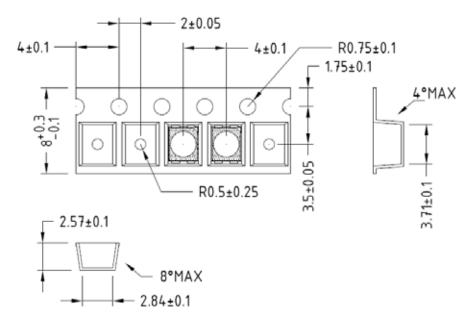




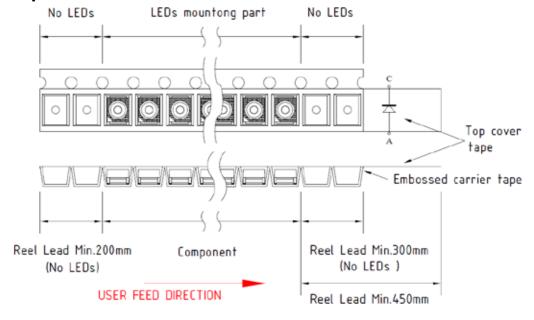


PACKAGING SPECIFICATION

Tape Dimension



Tape Leader and Trailer Dimension



Notes:

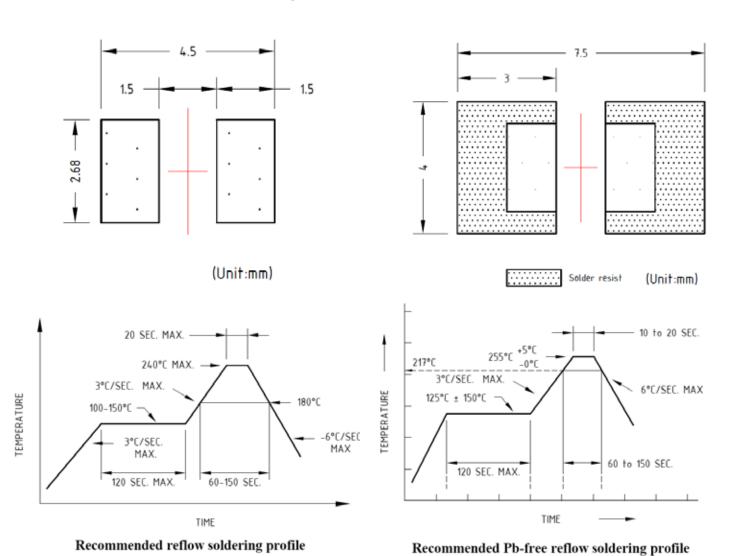
- 1. Empty component pockets are sealed with top cover tape
- 2. The maximum number of missing lamps is two.
- 3. 2000 pcs/reel





SOLDERING CONDITIONS

Recommended Soldering Pad Pattern



- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do no put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

